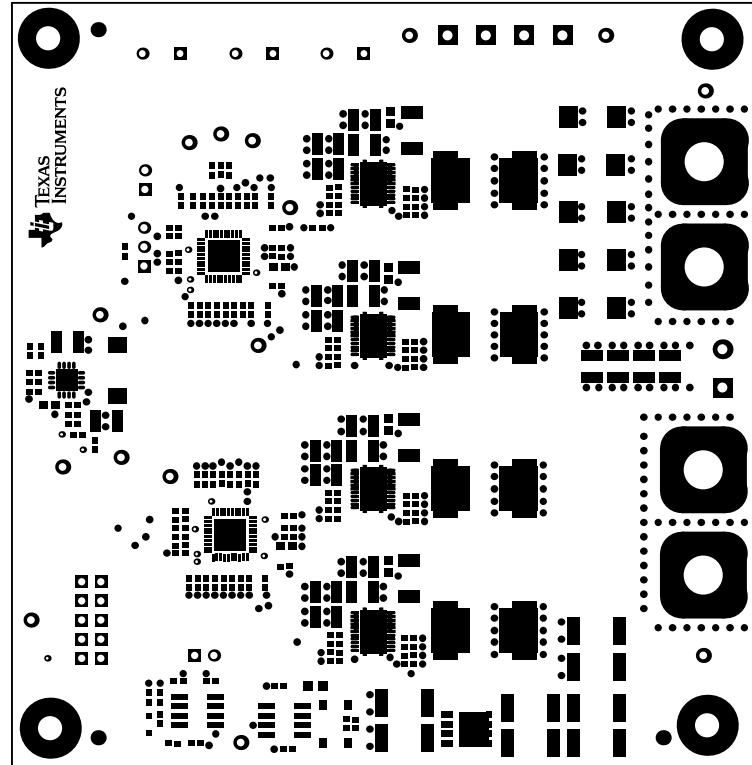
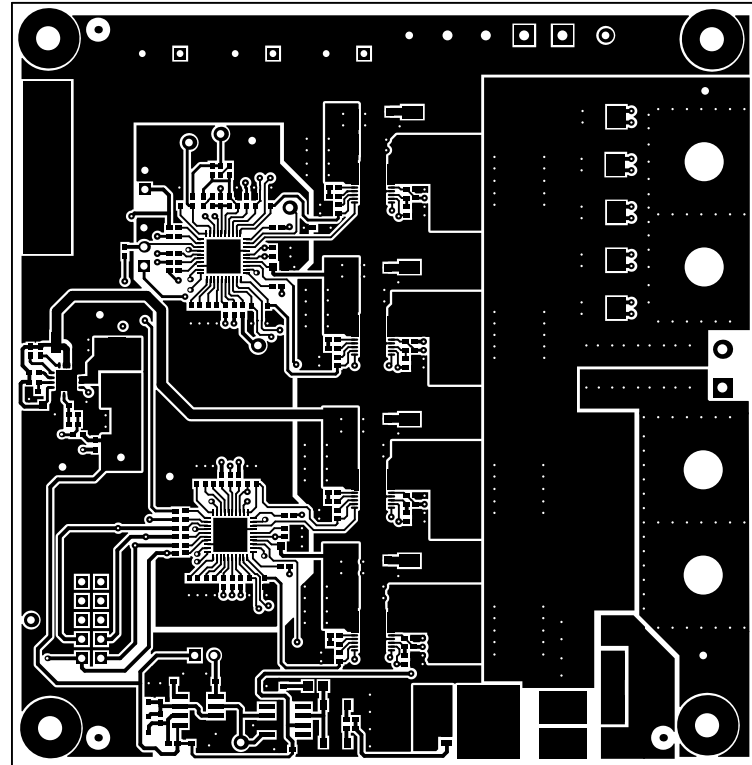


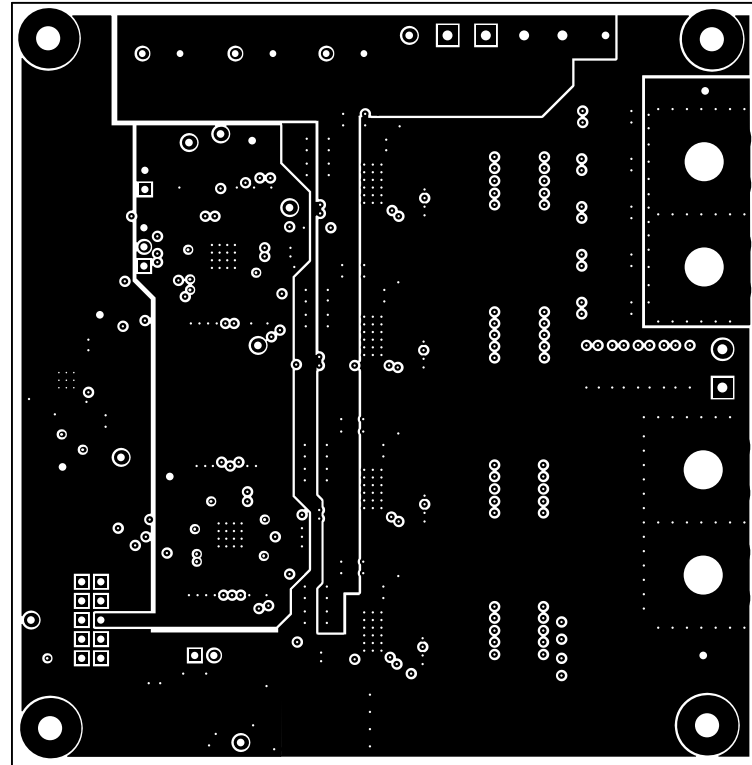
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 12/16/2013 1:59:35 PM	TEXAS INSTRUMENTS	



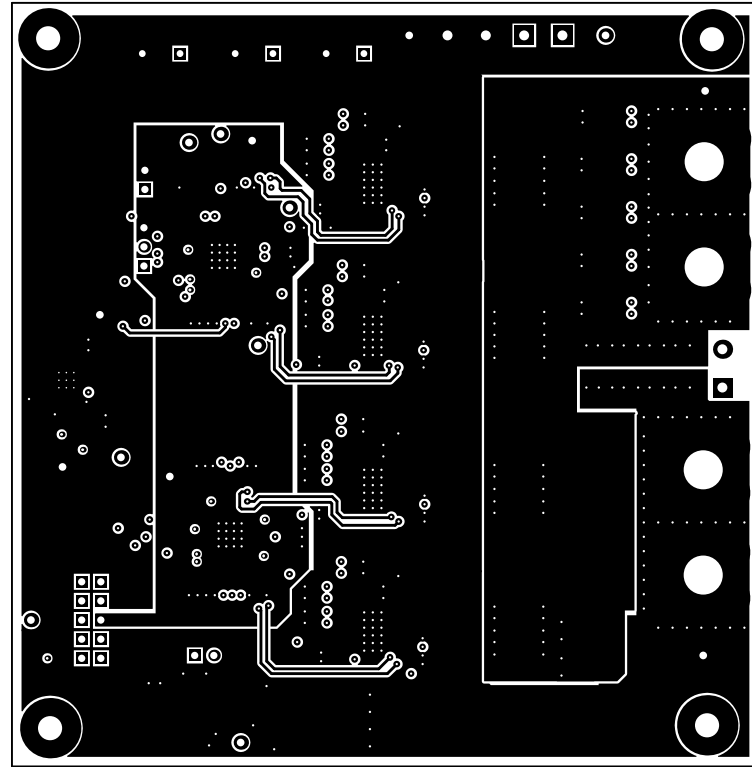
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 12/16/2013 1:59:36 PM	TEXAS INSTRUMENTS	



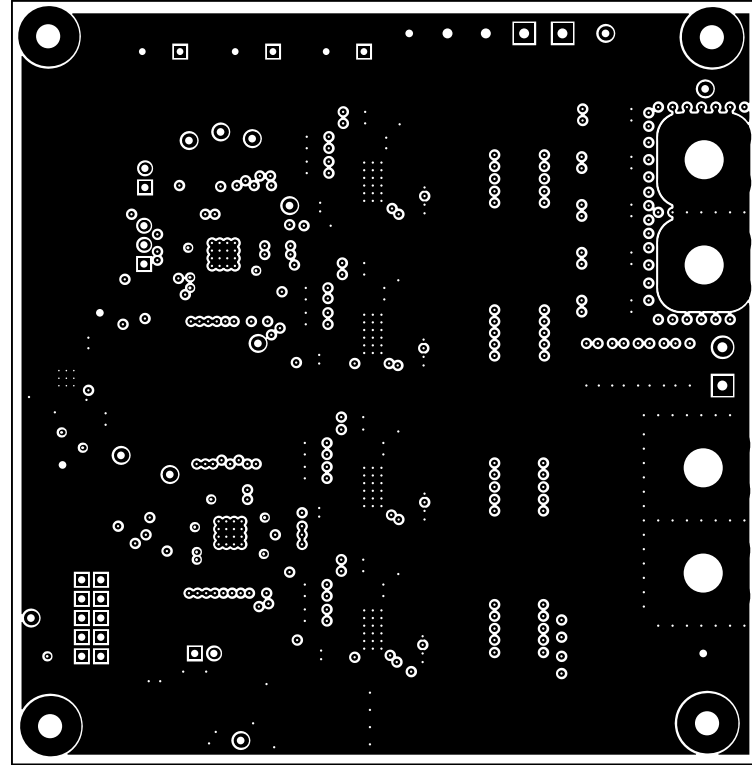
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 12/16/2013 1:59:36 PM	TEXAS INSTRUMENTS	



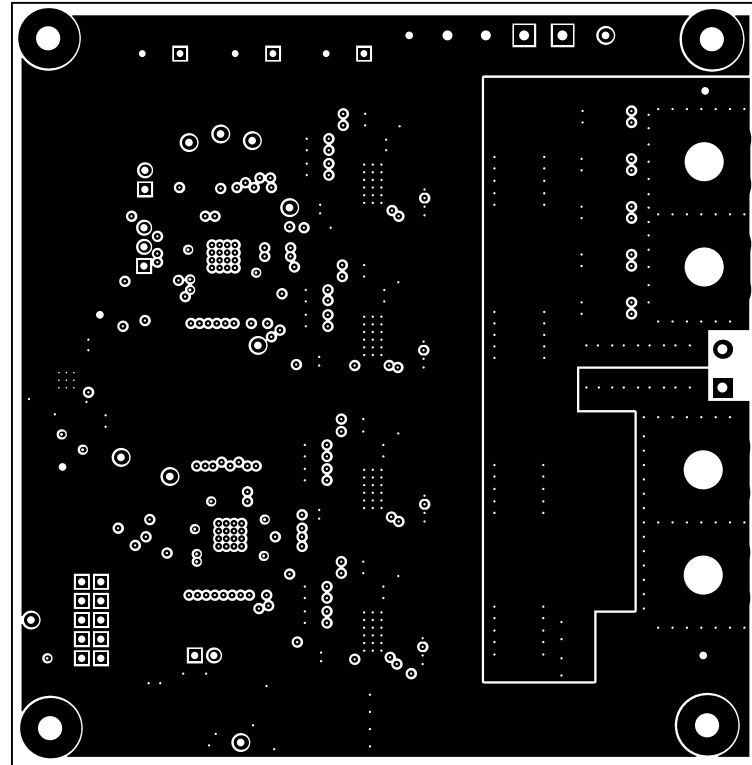
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M1 Board Outline			
PLOT NAME = Mid Layer 1	GENERATED : 12/16/2013 1:59:37 PM	TEXAS INSTRUMENTS	



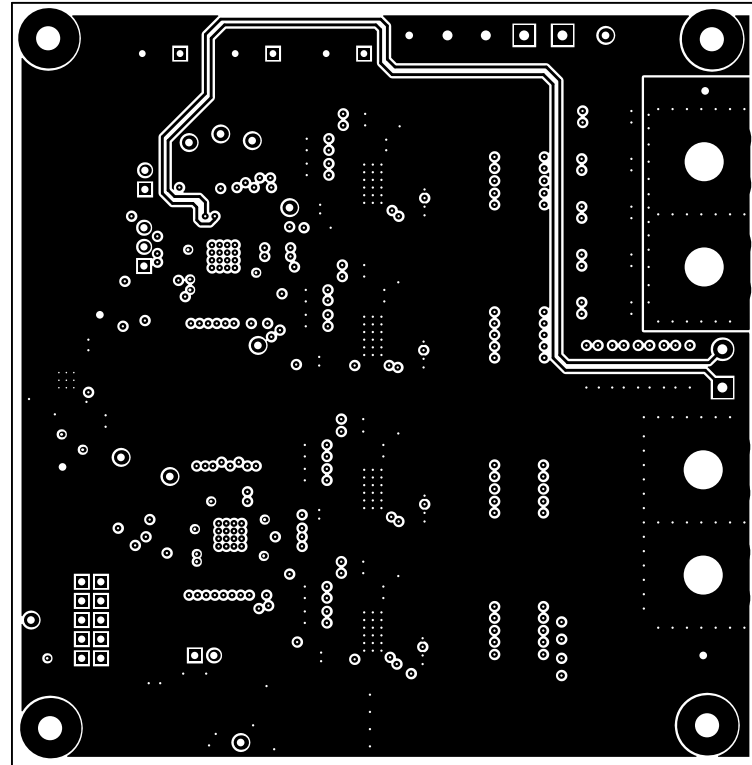
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M1 Board Outline			
PLOT NAME = Mid Layer 2	GENERATED : 12/16/2013 1:59:38 PM	TEXAS INSTRUMENTS	



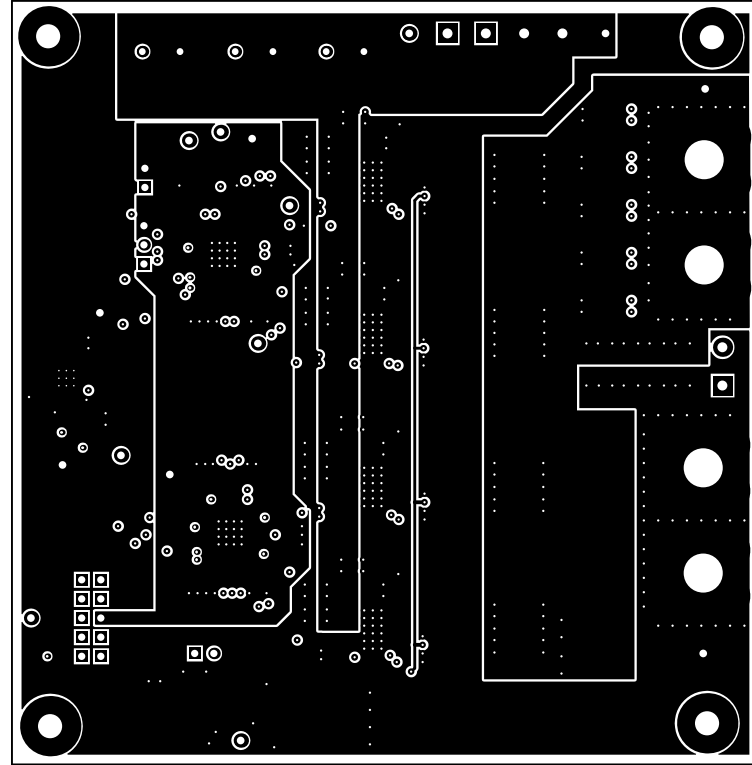
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M1 Board Outline			
PLOT NAME = Mid Layer 3	GENERATED : 12/16/2013 1:59:38 PM	TEXAS INSTRUMENTS	



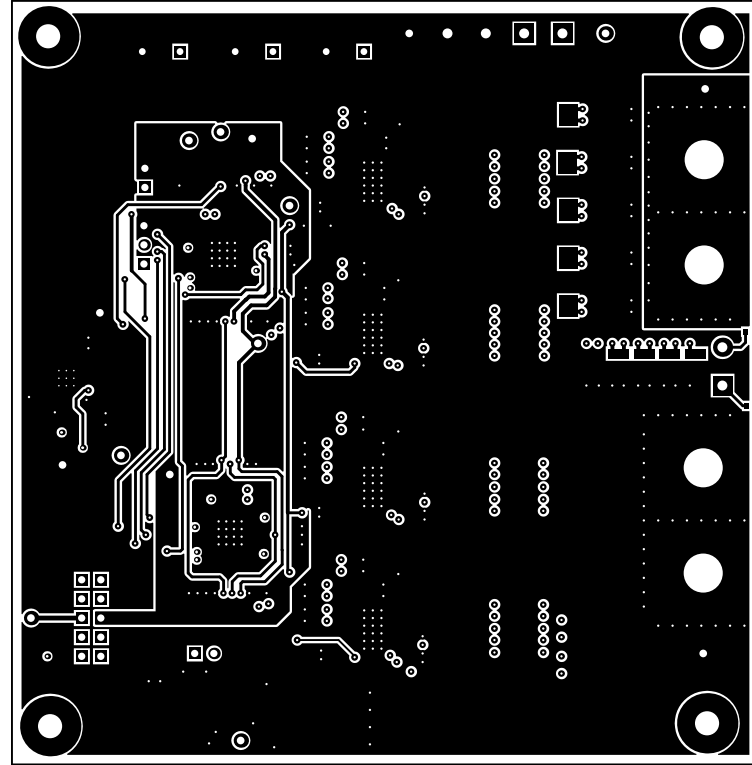
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M1 Board Outline			
PLOT NAME = Mid Layer 4	GENERATED : 12/16/2013 1:59:39 PM	TEXAS INSTRUMENTS	



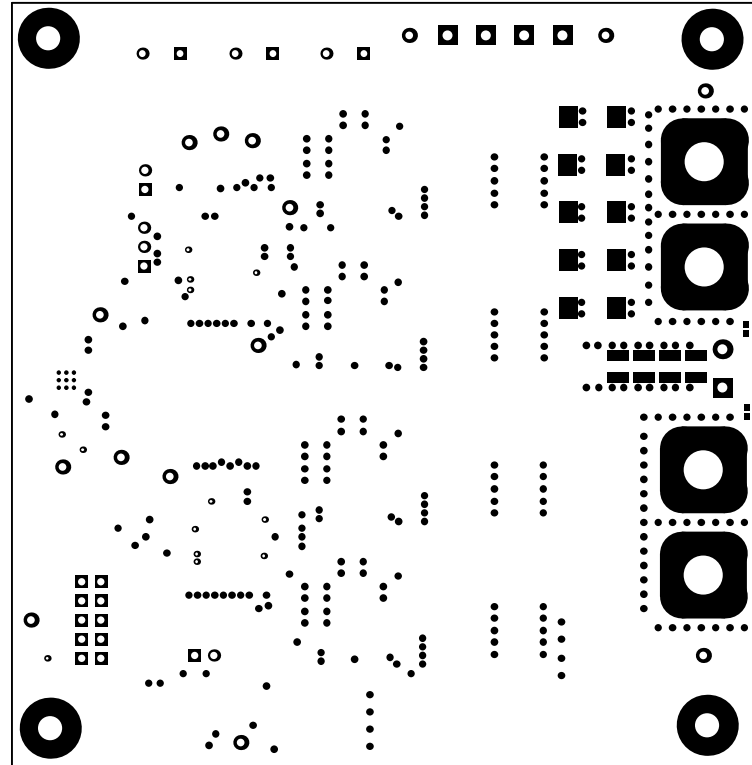
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M1 Board Outline			
PLOT NAME = Mid Layer 5	GENERATED : 12/16/2013 1:59:39 PM	TEXAS INSTRUMENTS	



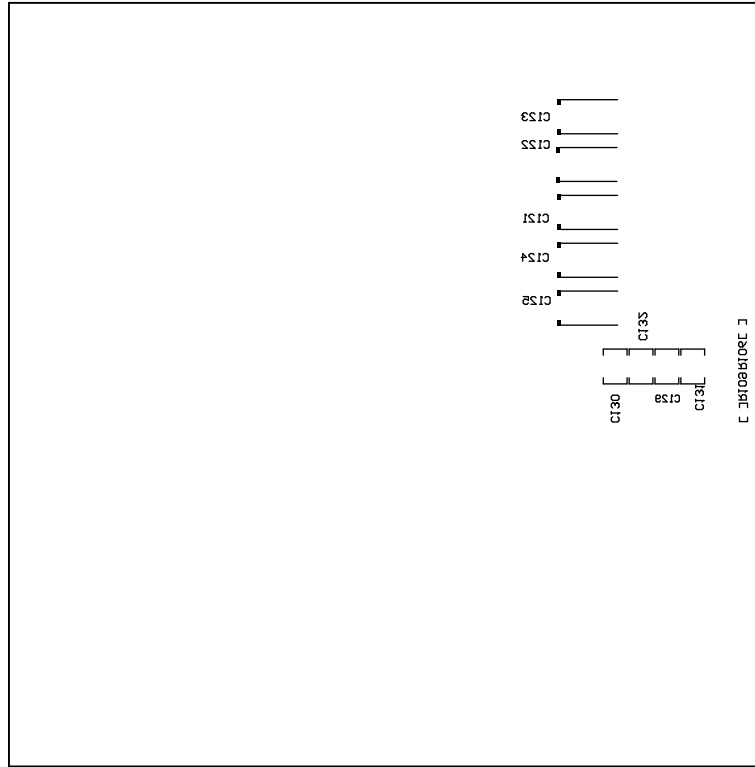
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M1 Board Outline			
PLOT NAME = Mid Layer 6	GENERATED : 12/16/2013 1:59:40 PM	TEXAS INSTRUMENTS	



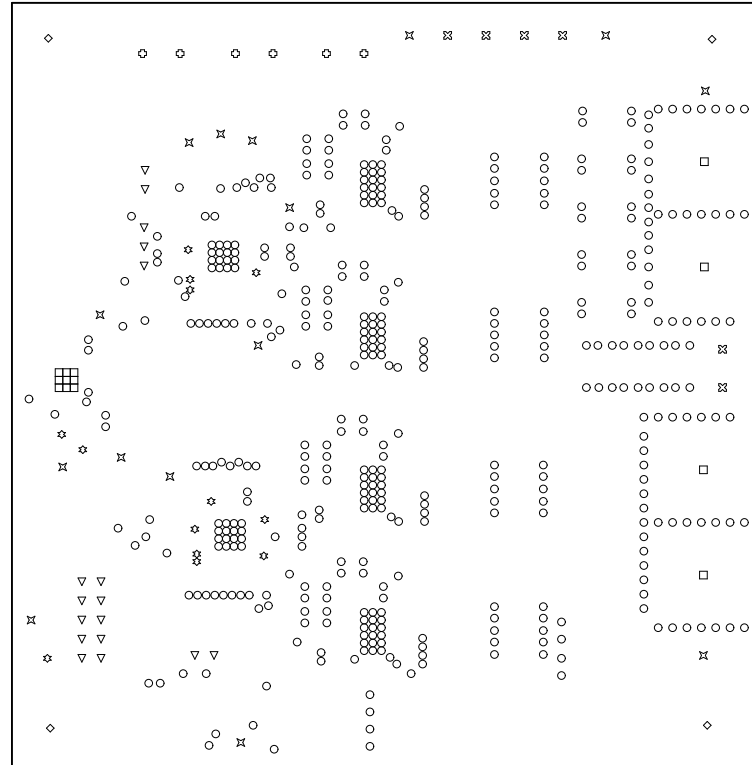
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 12/16/2013 1:59:40 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 12/16/2013 1:59:41 PM	TEXAS INSTRUMENTS	



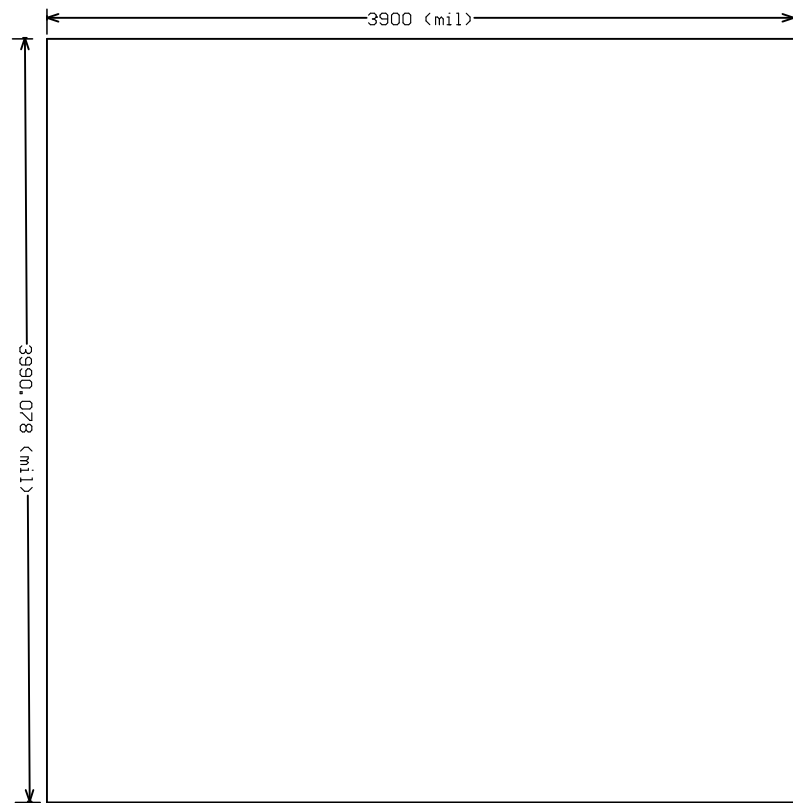
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 12/16/2013 1:59:42 PM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
□	9	7.874mil (0.2mm)	PTH	Round
○	441	12mil (0.305mm)	PTH	Round
☆	13	15mil (0.381mm)	PTH	Round
⊕	6	35.433mil (0.9mm)	PTH	Round
▽	17	38mil (0.965mm)	PTH	Round
⊗	15	40mil (1.016mm)	PTH	Round
⊗	6	52mil (1.321mm)	PTH	Round
◇	4	125.984mil (3.2mm)	PTH	Round
□	4	204mil (5.182mm)	PTH	Round
515 Total				

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 12/16/2013 1:59:42 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	←1000 (mil)→		
PLOT NAME = Board Dimensions	GENERATED : 12/16/2013 1:59:43 PM	TEXAS INSTRUMENTS	

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